

YW-PLS Series

PACKAGE LASER SAW SYSTEM

High Speed Precision Control system

Real Time Monitoring Vision System

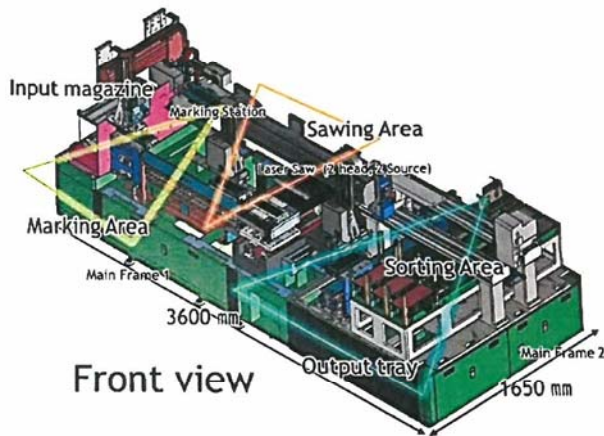
User Friendly GUI System

Package Laser Saw

半导体 Package Epoxy Molded Compound 的成型部位及 PCB (Printer Circuit Board)
Laser beam 利用改质层别 Cutting 的 Package Laser Saw System

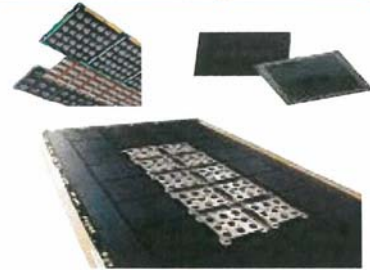
- ✓ Package Blade Saw Speed 对比 Capa 30% Up
- ✓ 微米单位超精密加工及精巧曲面加工性优秀
- ✓ Package Marking & Package Saw 一元化设备

Package Laser Saw System

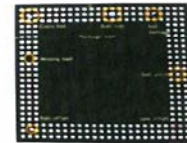


Laser : 2 Head 2 source

Package Marking & Sawing



Quality Vision Detect



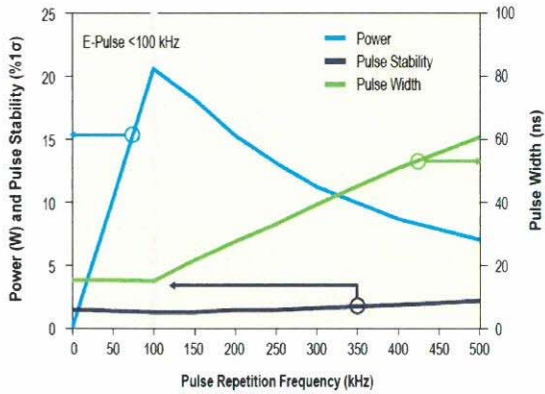
Solder Ball Quality
Ball Offset / Damage
Ball Size & Pitch
Scratch
Package Dimension
Ball Offset
Package Chips

Package Laser Saw 사양

| YW-PLS1000 | |
|----------------|---|
| 结构 | Marking + Dicing Saw 整体型设备 |
| 对象 Device | FBGA, MCP, CSP, Mobile PKG |
| 使用 Device Size | Max. 250(L) x 100(W) |
| 使用 最小 PKG Size | Min. 2.5(L) x 2.5(W) |
| MAZ 答应 | Width 100mm 基准 4 ea |
| 使用 Tray | JEDEC / EIAJ |
| UPH | Max. 8k (64Unit/1Strip) |
| MTBA | 240Min |
| Vision | Ball, Mark, PKG Vision 12MEGA Pixel Camera 使用 |
| 设备 Size | 3600 x 1650 x 1850mm (W x L x H) |
| COK Time | 10Min |

Laser Source Type

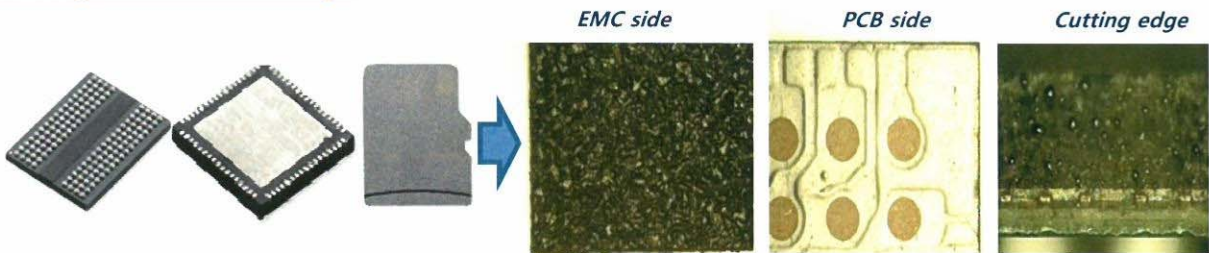
Typical Power and Pulse Stability – Talon 355-20



Laser configuration

| System Configuration | |
|----------------------|--|
| System Model | CF430 UV |
| System S/L# | MV15026 |
| Laser Model | Talon 355-20 |
| Wavelength | 355 nm |
| Pulse Width | 20 ns @ 100KHz |
| Repetition Rate | 0 ~ 500KHz |
| Power | 20W @ 100KHz for 355-20 |
| Spot Size | 20um |
| Laser Control | Laser Internal Attenuator (Displayed As %) |
| Beam Shape | Gaussian |

Package Laser Saw Image



Laser Saw 单面 Roughness

